

**CLAIMS**

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**IN THE CLAIMS:**

- Claim 1 (Previously presented) A structure comprising:
- a substrate having a surface;
  - a plurality of bond wire elongated electrical conductors extending away from said surface;
  - each of said bond wire elongated electrical conductors having a first end affixed to said surface at an electrical contact location and a second end projecting away from said surface;
  - there being a plurality of said second ends;
  - said first end and said second end of said bond wire elongated electrical connector having a ball-shaped protuberance positioned thereon;
  - means for permitting each of said plurality of said second ends to move about reference positions;
  - wherein said means for permitting each of said plurality of second ends to move about reference positions is a sheet of material having a plurality of through-holes therein through which said second ends project, there being a perforation in each said sheet in the vicinity of said openings. --
- Claims 2- 3 (Cancelled)
- Claim 4. (Previously presented) The structure according to claim 1 wherein said perforation comprises a plurality of independent perforations about each of said through hole.-
- Claim 5. (Previously presented) The structure according to claim 1 wherein said perforation comprises a plurality of independent perforations about at least a part of said plurality of through-holes. --
- Claim 6. (Previously presented) The structure according to claim 1 wherein said perforation is a portion coupled to an adjacent through-hole. --

– Claim 7. (Previously presented) The structure according to claim 1 wherein said perforation is adjacent to a plurality of said through-holes. –

– Claim 8. (Currently Amended) The structure according to claim 3 1 wherein said perforations form a cantilevered flap about at least one of said through-holes. –

– Claim 9. (Previously presented) The structure according to claim 1 wherein a plurality of said perforations form cantilevered flaps about more than one of said through-holes –

– Claim 10. (Previously presented) The structure according to claim 1 wherein at said second end there is disposed a structure selected from the group consisting of a protuberance and a sharp. –

– Claim 11. (Previously presented) The structure according to claim 3 1 wherein at said second end there is disposed a structure selected from the group consisting of a protuberance and a sharp. –

--Claim 12. (Previously presented) The structure according to claim 1 wherein said sheet comprises a sheet of electrically conductive material having a plurality of through holes therein, said sheet of material contains a dielectric material to provide a means for preventing said elongated electrical conductors from electrically contacting said sheet of electrically conductive material. –

--Claim 13. (Previously presented) The structure according to claim 1 wherein said sheet is spaced apart from said surface by a flexible support.

--Claim 14. (Previously presented) The structure according to claim 13 wherein said flexible support is selected from the group consisting of a spring and an elastomeric material.

--Claim 15. (Previously presented) The structure according to claim 1 wherein said elongated electrical conductors have a shape selected from the group consisting of linear piecewise linear, curved and combinations thereof.

--Claim 16. (Previously presented) The structure according to claim 13 wherein said sheet and said flexible support form a space containing said plurality of elongated electrical conductors

--Claim 17. (Previously presented) The structure according to claim 16 wherein said space is filled with a flexible material.

--Claim 18. (Previously presented) The structure according to claim 17 wherein said flexible material is an elastomeric material.

--Claim 19. (Previously presented) The structure according to claim 12 wherein said sheet has a top surface and a bottom surface and said through holes have a sidewall, said dielectric material coats said top surface and said bottom surface and said sidewall.

--Claim 20. (Previously presented) A structure according to claim 1 wherein said plurality of elongated electrical conductors are distributed into a plurality of groups.

--Claim 21 (Previously presented) The structure according to claim 20 wherein said plurality of groups are arranged in an array.

--Claim 22. (Previously presented) The structure according to claim 1 wherein said structure is a probe for an electronic device.

--Claim 23. (Previously presented) The structure according to claim 22 wherein said electronic device is selected from the group consisting of an integrated circuit and a

packaging substrate.

--Claim 24. (Previously presented) The structure according to claim 21 wherein each of said groups corresponds to an integrated circuit chip on a substrate containing a plurality of said integrated circuit chips.

--Claim 25. (Previously presented) The structure according to claim 24 wherein said substrate containing said plurality of integrated circuit chips is a wafer of said integrated circuit chips.

--Claim 26. (Previously presented) An apparatus for using said structure of claim 1 to test an electronic device comprising:  
means for holding said structure of claim 1;  
means for retractable moving said structure of claim 1 towards and away from said electronic device so that said second ends contact electrical contact locations on said electronic device; and  
means for applying electrical signals to said elongated electrical conductors.

--Claim 27. (Previously presented) A structure according to claim 10 wherein said protuberance is spherelike.

--Claim 28. (Previously presented) The structure according to claim 1 wherein said sheet comprises a sheet of electrically conductive material having a plurality of through holes therein, and a sheet of dielectric material having a plurality of second through holes therein, said first through holes are aligned with said second through holes, said first through holes have a smaller diameter than said second through holes to provide a means for preventing said elongated electrical conductors from electrically contacting said sheet of electrically conductive material. –

--Claim 29. (Previously presented) The structure according to claim 28 wherein said sheet of electrically conductive material has a first side and a second side, said sheet of

dielectric material is disposed on either of said first side and said second side of said sheet of electrically conductive material.

--Claim 30. (Previously presented) The structure according to claim 29 where there is disposed on said first side and said second side of said sheet of electrically conductive material, a layer of said dielectric material.

--Claim 31. (Previously presented) The structure according to claim 1 wherein said sheet comprises a sheet of rigid material having a plurality of through holes therein, said sheet contains a dielectric material to provide a means for preventing said elongated electrical conductors from electrically contacting said sheet of electrically conductive material. --

--Claim 32. (Currently amended) A ~~The~~ structure according to claim ~~3~~ 1 wherein said sheet comprises a sheet of dielectric material having a plurality of through holes therein, said sheet contains a sheet of rigid material disposed in contact with said sheet of dielectric material, said sheet of rigid material has an opening therein exposing a plurality of said through holes to provide means for support of said dielectric material.

--Claim 33. (Previously presented) The structure according to claim 31 wherein said sheet is spaced apart from said surface by a flexible support, said sheet of rigid material is disposed on said flexible support.

Claim 34 (Canceled) An apparatus for making electrical contact with a plurality of bond pads on an integrated circuit device comprising:  
an integrated cantilevered compliant test probe comprising:  
a first fanout substrate having a first surface;  
said first surface having a plurality of contact locations;  
a plurality of ball bonds attached to said plurality of contact locations;  
a plurality of free-standing wires extending outward from said ball bonds away from said first

surface on said fan out substrate;  
a plurality of ball shaped contacts on the ends of said plurality of wires;  
a cantilevered flap means for controlling the direction and length of each of said plurality of ball shaped contacts to move about corresponding reference positions, the configuration of elements of said apparatus being such that the movement of said wires is always in the same direction with continuous contact at said contact locations.

--Claim 35. (Canceled) The apparatus according to claim 34 wherein said fan out substrate type comprises:  
multilayer ceramic substrates with thick film wiring;  
multilayer ceramic substrates with thin film wiring;  
metallized ceramic substrates with thin film wiring;  
epoxy glass laminate substrates with copper wiring;  
silicon substrates with thin film wiring.

--Claim 36. (Canceled) The apparatus according to claim 34 further including a preformed frame of foamed elastomer material surrounding clusters groupings or arrays of said probes.

--Claim 37 (Canceled) The apparatus according to claim 36 further including a layer of elastomer material surrounding said probes in said cluster.

--Claim 38. (Canceled) The apparatus according to claim 37 further including a sheet of Invar material that has a thin coating of a polymer material and a plurality of openings corresponding to said plurality of ball shaped contacts.

--Claim 39. (Canceled) The apparatus according to claim 37 further including

a sheet of Invar material with a plurality of large diameter openings corresponding to said plurality of ball shaped contacts.

--Claim 40. (Canceled) The apparatus according to claim 37 further including a sheet of polymer material with a plurality of small diameter openings corresponding to said plurality of ball shaped contacts placed on top of said sheet of Invar material.

--Claim 41. (Canceled) The apparatus according to claim 37 further including a sheet of polymer material with a plurality of small diameter openings corresponding to said plurality of ball shaped contacts.

--Claim 42. (Canceled) The apparatus according to claim 41 further including a frame attached to said sheet of polymer material with said plurality of openings corresponding to said plurality of ball shaped contacts.

--Claim 43. (Canceled) The apparatus according to claim 38 further including a thick frame of Invar material attached to said sheet of Invar material with said thin coating of a polymer material and said plurality of openings corresponding to said plurality of ball shaped contacts.

--Claim 44. (Canceled) The apparatus according to claim further including a plurality of probes arrays corresponding to the location of a plurality of IC devices on a wafer.

--Claim 45. (Canceled) The apparatus according to claim 36, further including a sheet of Invar material that has a thin coating of polymer material and a plurality of openings corresponding to said plurality of ball shaped contacts.



--Claim 46. (Previously presented) A method comprising:  
providing a substrate having a surface;  
forming a plurality of bond wire elongated electrical conductors extending away from said surface;  
each of said bond wire elongated electrical conductors having a first end affixed to said surface at an electrical contact location and a second end projecting away from said surface;  
there being a plurality of said second ends;  
said first end and said second end of said bond wire elongated electrical connector having a ball-shaped protuberance positioned thereon;  
providing means for permitting each of said plurality of said second ends to move about reference positions;  
wherein said means for permitting each of said plurality of second ends to move about reference positions is a sheet of material having a plurality of through-holes therein through which said second ends project, there being a perforation in each said sheet in the vicinity of said openings. --

--Claim 47. (Previously presented) The structure according to claim 1 wherein said sheet is formed from a material selected from the group consisting of Invar, Cu/Invar/Cu, molybdenum, polyimides.

--Claim 48. (Previously presented) The structure according to claim 1 wherein said sheet is formed from a material selected from the group consisting of metal, a polymer, semiconductor and dielectric.

--Claim 49. (Currently amended) The structure according to claim ~~42~~ 48 wherein said dielectric is selected from the group consisting of a ceramic and a glass.

--Claim 50. (Canceled) An apparatus for making electrical contact with a plurality of aluminum bond pads on an integrated circuit device comprising:  
an integrated cantilevered compliant test probe comprising:  
a first fan-out substrate having a first surface;  
said first surface having a plurality of contact locations;  
a plurality of ball bonds attached to said plurality of contact locations;  
a plurality of free standing wires extending outward from said ball bonds, away from said first surface on said fan-out substrate;  
a plurality of ball shaped contacts on the ends of said plurality of wires;  
cantilevered flap means for controlling the direction and length of each of said plurality of ball shaped contacts to move about corresponding reference positions, the configuration of elements of said apparatus being such that the movement of said wires is always in the same direction with continuous contact at said contact locations.

--Claim 51. (Canceled) The apparatus according to claim 50 wherein said fan-out substrate type is selected from the group consisting of:  
multilayer ceramic substrates with thick film wiring;  
multilayer ceramic substrates with thin film wiring;

metallized ceramic substrates with thin film wiring;  
epoxy glass laminate substrates with copper wiring;  
silicon substrates with thin film wiring.

Claim 52. (Previously presented) The structure according to claim 1, further including a layer of elastomer material surrounding said ball shaped protuberances positioned at said first end of said bond wire elongated electrical conductors and a substantial portion of said bond wire elongated electrical conductors.

Claim 53. (Previously presented) The structure according to claim 9, wherein said means for permitting each of said plurality of second ends to move about reference positions is a sheet of polymer material with a plurality of cantilever flaps and openings corresponding to said plurality of said second end ball-shaped protuberances.

Claim 54. (Previously presented) The structure according to claim 53, further including an epoxy material used to bond the plurality of ball shaped protuberances to the corresponding openings in said cantilever flaps.

Claim 55. (Previously presented) The structure according to claim 5 wherein the action of mating said plurality of said second end ball-shaped protuberances to a plurality of flat or recessed contacts on an IC device causes said plurality of second end ball shape protuberances to wipe against said IC contacts.

Claim 56. (Previously presented) The structure according to claim 1, further including a plurality of cylindrical collars concentrically located on the plurality of probe wires and positioned between the top surface of said elastomer material and said second end ball shape

protuberances on the end of said probe wires.

Claim 57. (Previously presented) The structure according to claim 9, wherein said means for permitting each of said plurality of second ends to move about reference positions is a sheet of polymer material with a plurality of openings corresponding to a plurality of cylindrical collars concentrically located on a plurality of probe wires.

Claim 58. (Previously presented) The structure according to claim 1, further including a plurality of probe arrays corresponding to the location of a plurality of IC devices on a wafer.

Claim 59. (Cancelled) A structure according to claim 3, wherein said means for permitting is a sheet of material having a plurality of openings therein through which said second ends project

Claim 60. (Currently amended) ★ The structure according to claim 46, further including a plurality of probes arrays corresponding to the location of a plurality of IC devices on a wafer.

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